

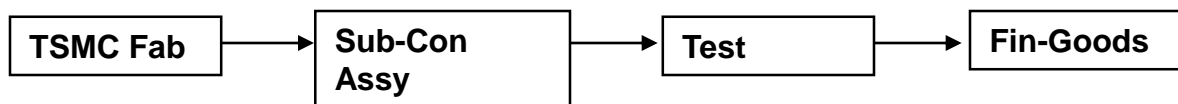
QUALIFICATION RESULTS SUMMARY OF FAB TRANSFER AT ADI PER PCN 17_0118			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	<b>1*77</b>	<b>Passed</b>
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	<b>1*77</b>	<b>Passed</b>
Autoclave	JEDEC <i>JESD22-A102</i>	<b>1*77</b>	<b>Passed</b>
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	<b>1*77</b>	<b>Passed</b>
Early Life Failure (ELF)	MIL-STD-883 <i>Method 1015</i>	<b>3*667</b>	<b>Passed</b>
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	<b>1*45</b>	<b>Passed</b>
Solder Heat Resistance (SHR)*	<i>ADI-0049</i>	<b>1*30</b>	<b>Passed</b>
Latch-Up	JEDEC <i>JESD78</i>	<b>6</b>	<b>Passed</b>
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JDS-001-2011</i>	<b>3/voltage</b>	<b>Passed</b>
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	<b>3/voltage</b>	<b>Passed</b>

\*Preconditioned per JEDEC/IPC J-STD-020



## Alternate fab source for RS-232 and RS-485/RS-422 Transceiver products. To enable additional wafer fabrication capacity

### Current Flow:



### Alternate Flow:

